

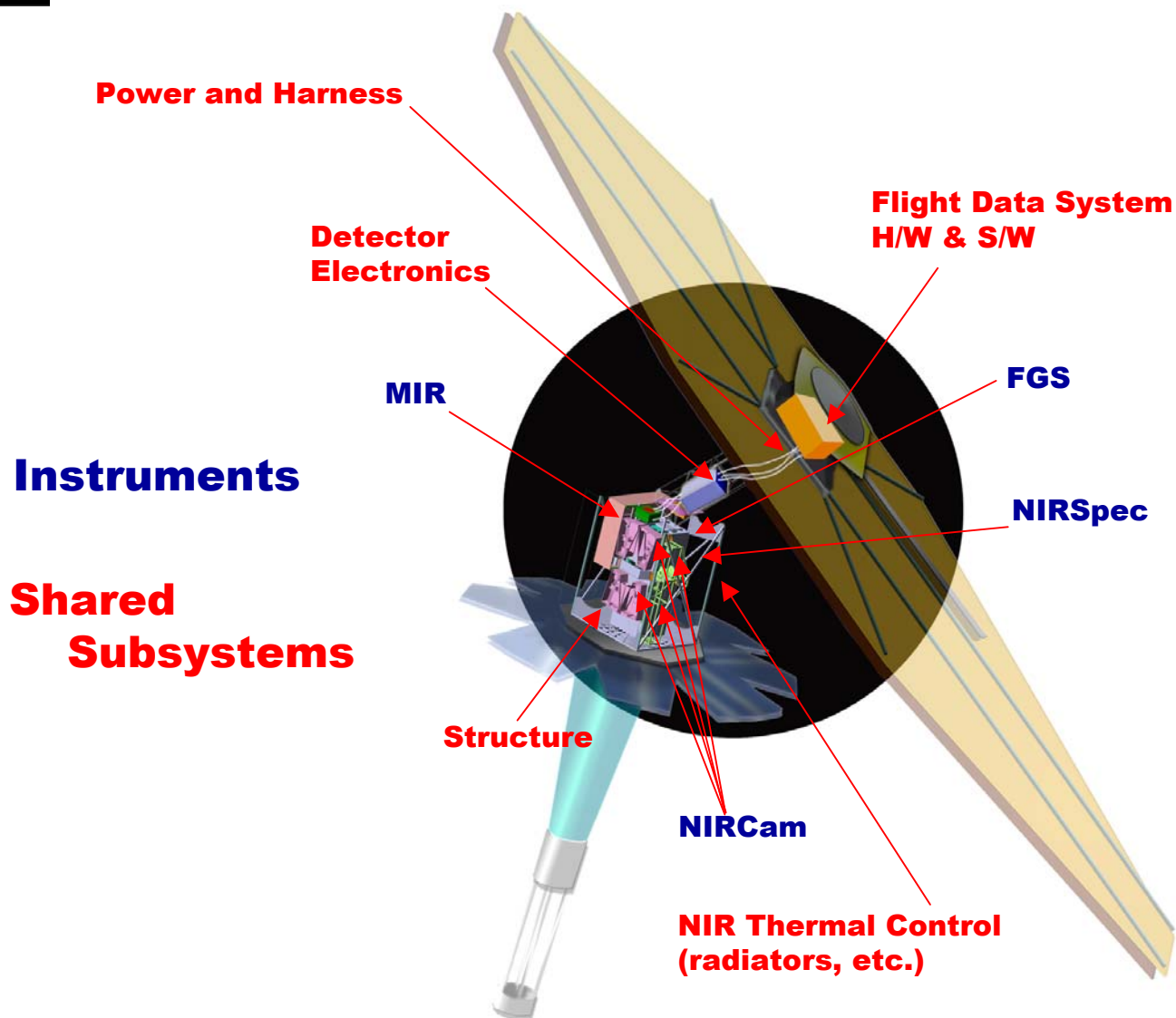


Integrated Science Instrument Module

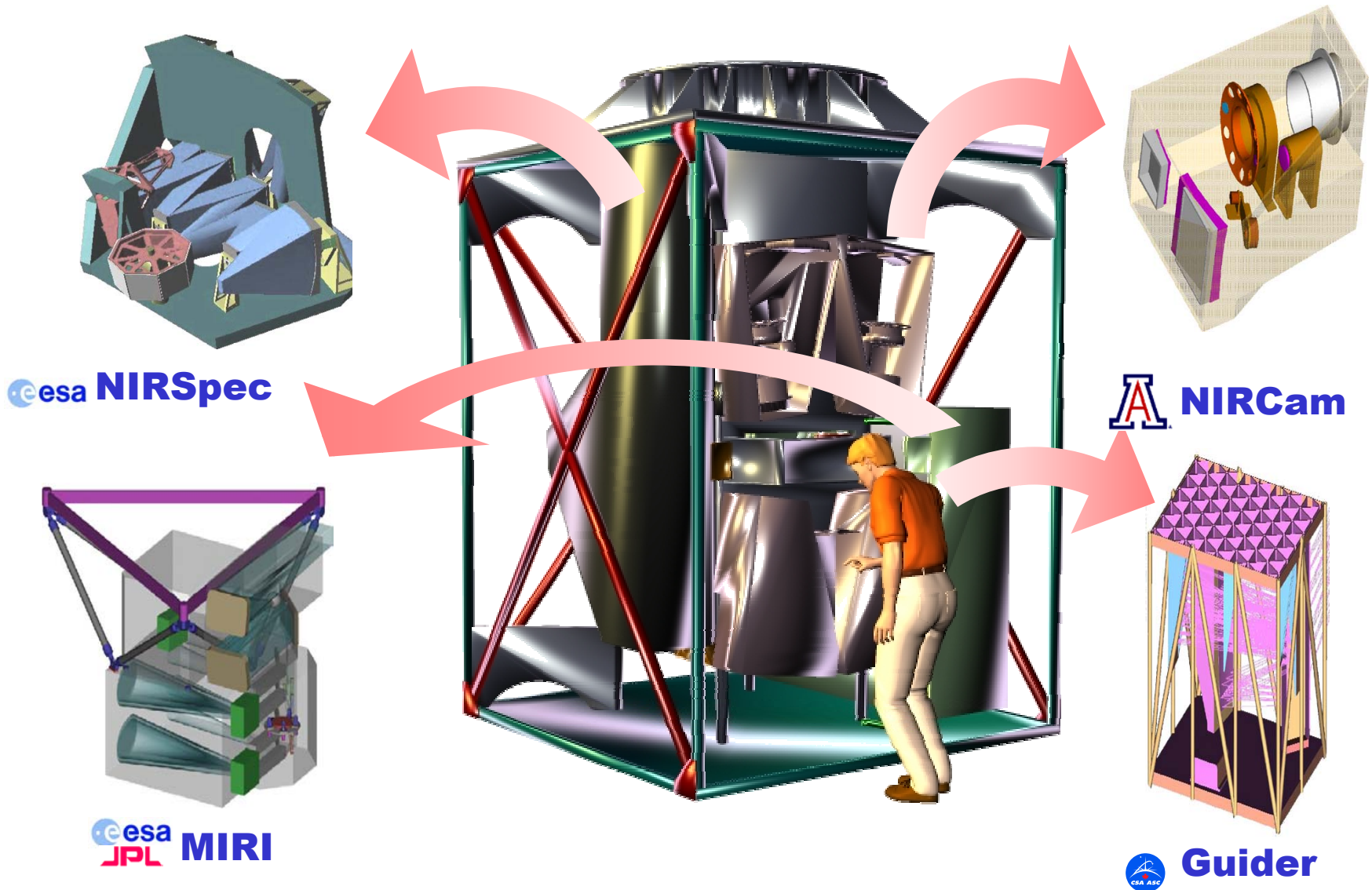
Presented by: Matt Greenhouse

23 September 2002

ISIM is the Payload of JWST



ISIM Cryogenic Portion



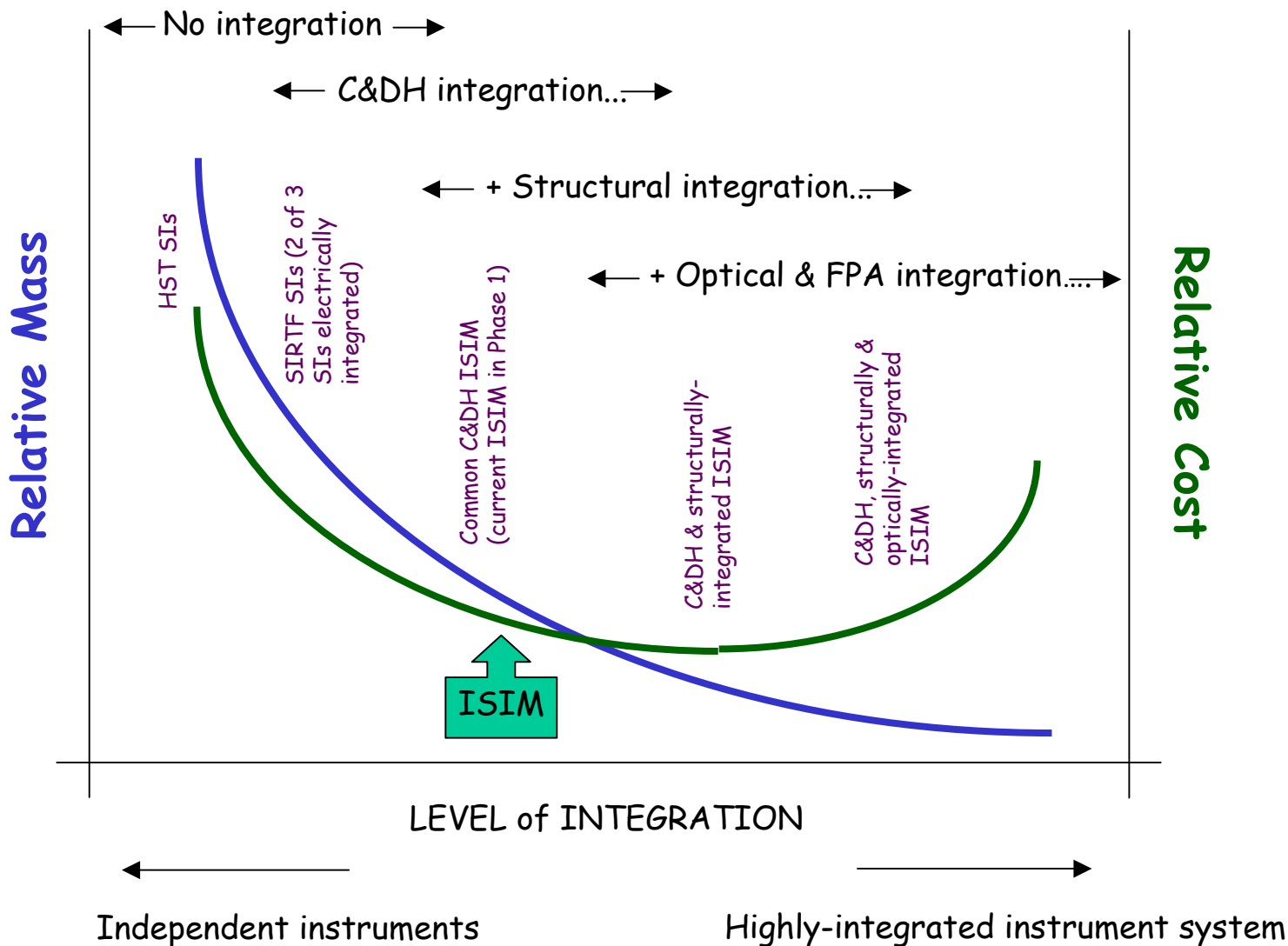


An Integrated SI Module Architecture Developed to Reduce Life Cycle Cost

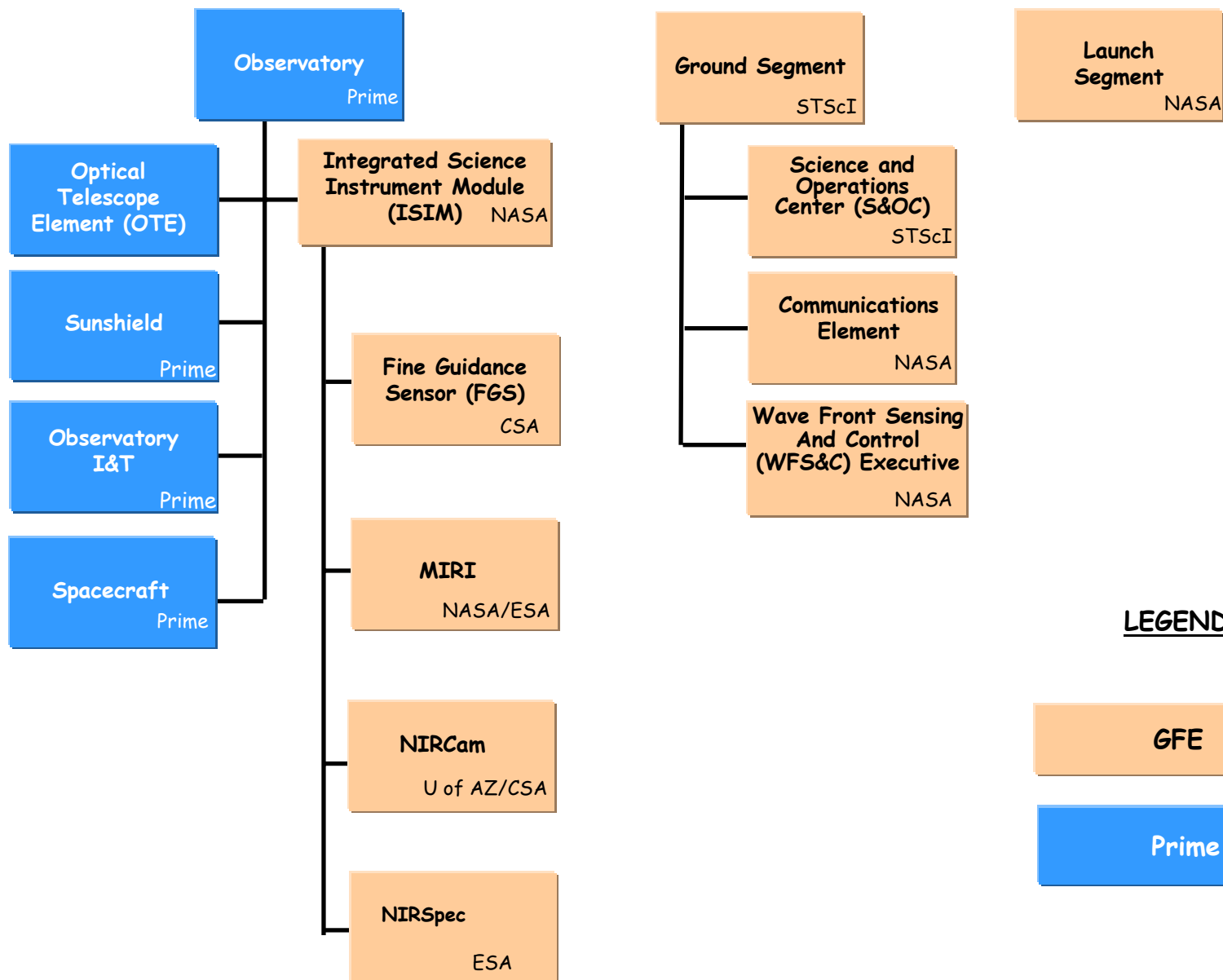


- Key life cycle cost (LCC) drivers include NRE, mass, I&T, and operations
- Flight cryogenic application provides unique challenges with respect to HST
 - Tight systems integration yields reduced NRE costs and system mass
 - Modular implementation and incremental testing yields reduced I&T costs (particularly for cryo-applications)
- Best value trade from phase A studies:
 - Limited systems integration implemented by consolidating components with common functions into common systems that are shared by all science instruments
 - Unique instrument systems and shared systems implemented in modular fashion
- Instrument system LCC is reduced ~30% by consolidating the instrument C&DH, detector electronics, and thermal management functions compared to a fully independent SI approach
 - High quality systems engineering and SI customer (PI & SWG) interaction are key to successful implementation of this approach

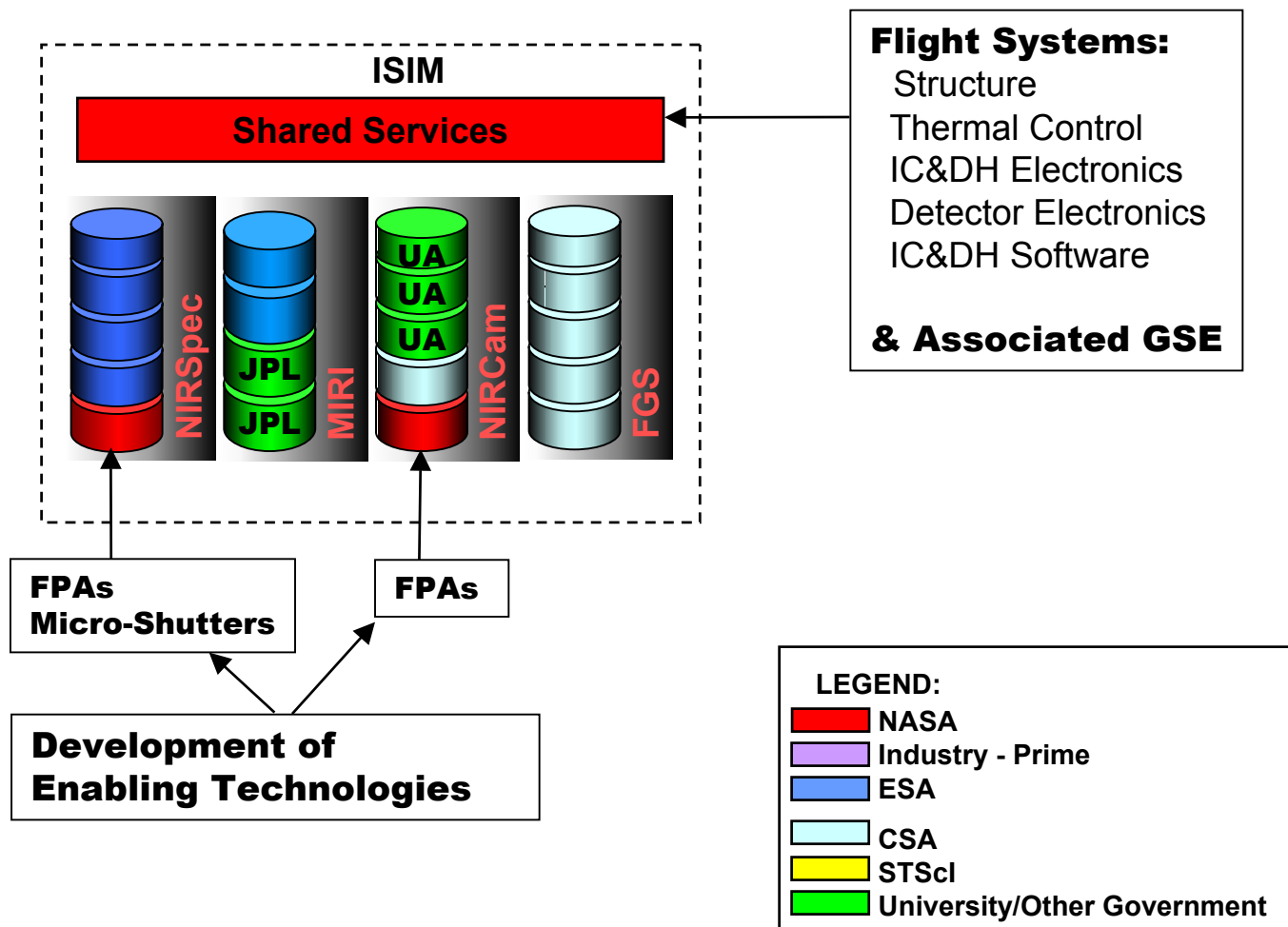
ISIM Mass and Cost vs. Integration



JWST Team Relationships



ISIM Team Relationships



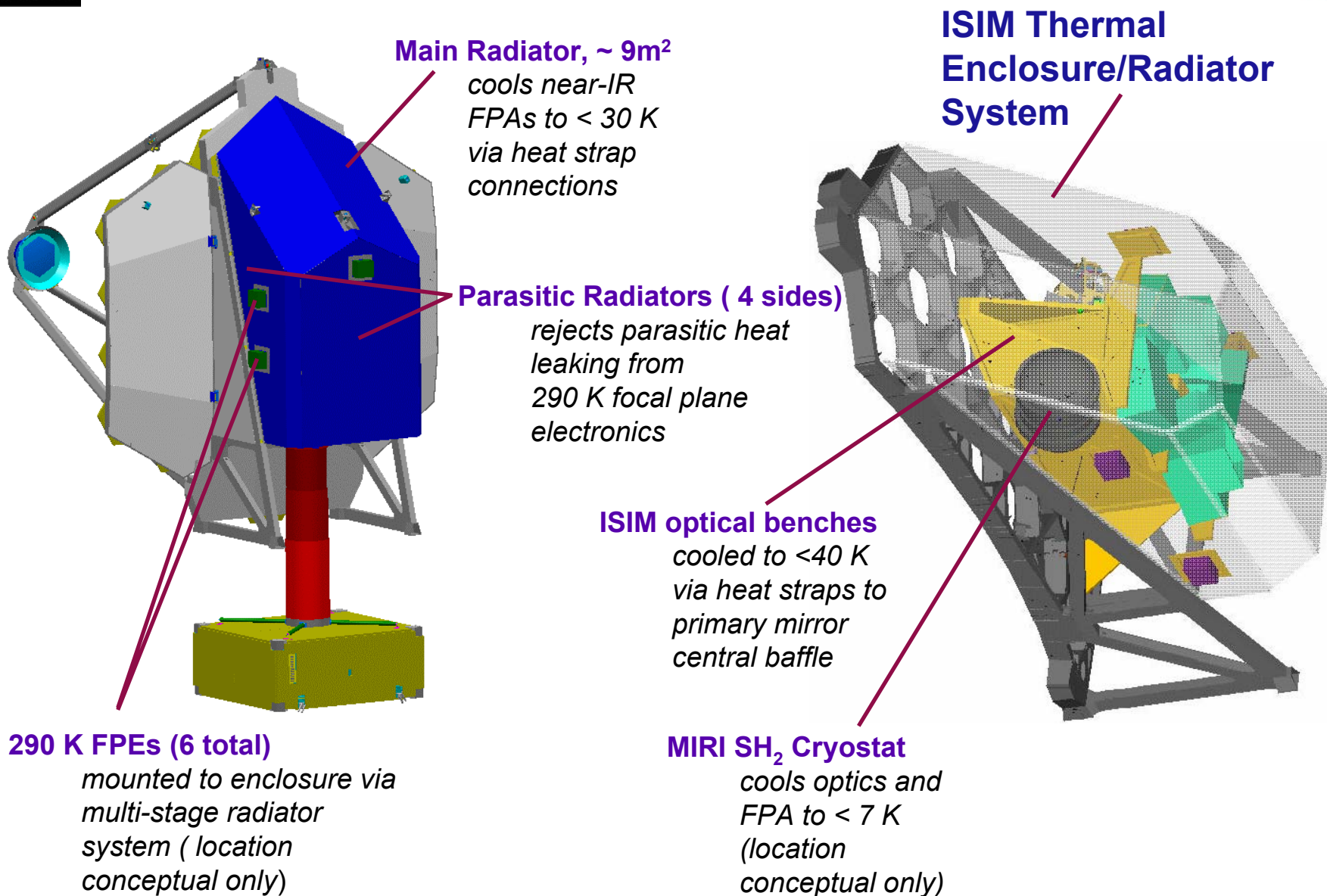


ISIM Structure



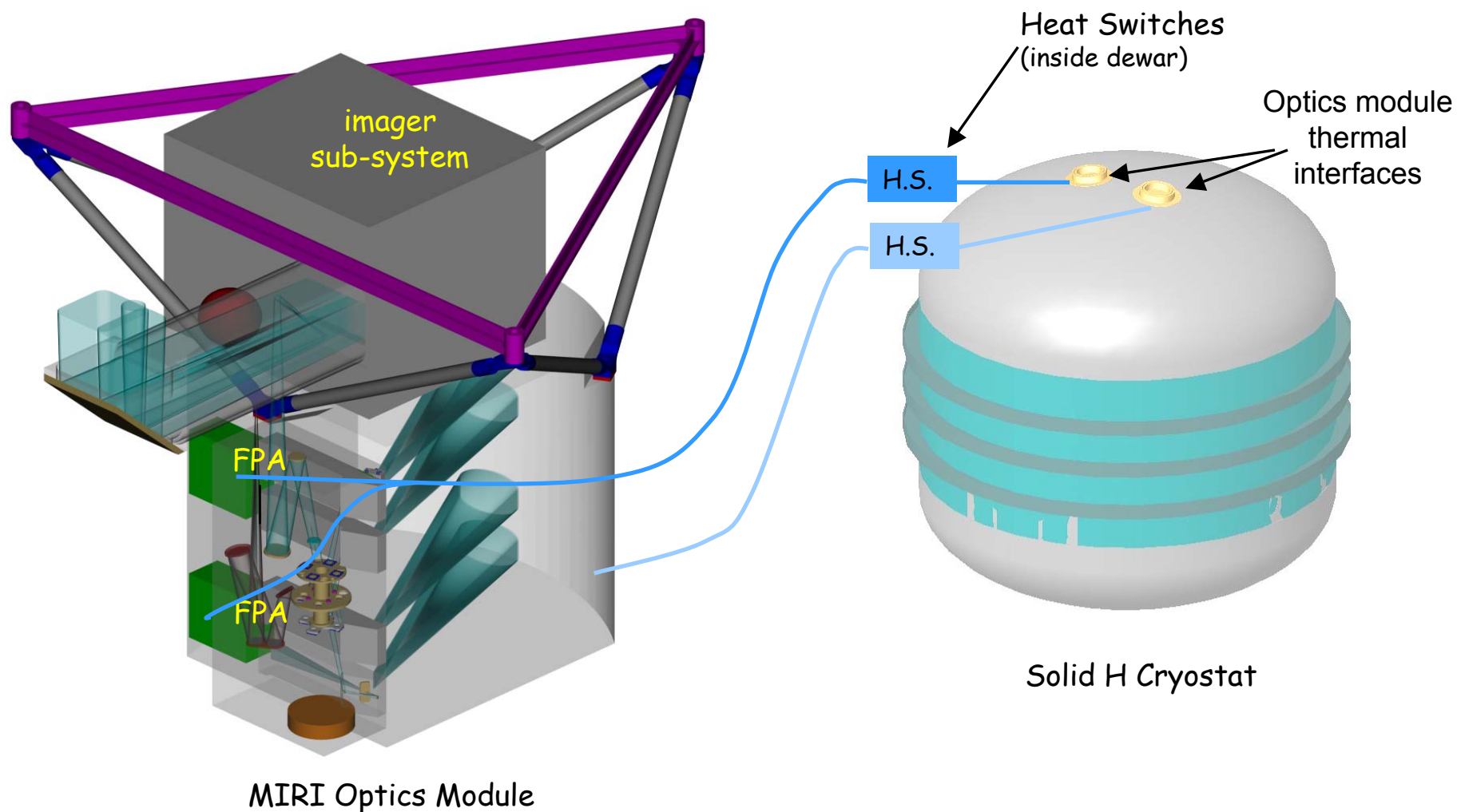
- Supporting structure that couples the NIRCам, NIRSpec, MIRI, FGS, Cryostat, SI pick-off mirrors, cold electronics and thermal radiators, heat straps, and electrical harness to the OTE
- Status:
 - **Current designs for all four instrument systems can be accommodated within the TRW ISIM control volume and mass allocation**
 - NIRCам, NIRSpec, MIRI w/ 10 year cryostat, FGS
 - Baseline instrument support structure has been designed and analyzed
 - Instrument packaging approach developed through face to face concurrent engineering meetings with MIRI, NIRSPEC, and FGS teams
 - First of many such concurrent design interactions
 - Performed structural materials study. Selected M55J GrEp system as baseline for ISIM Structure.
 - Development of structure verification plan developed to appropriate level
 - Instrument alignment stability

Phase 1 ISIM Thermal Control Concept

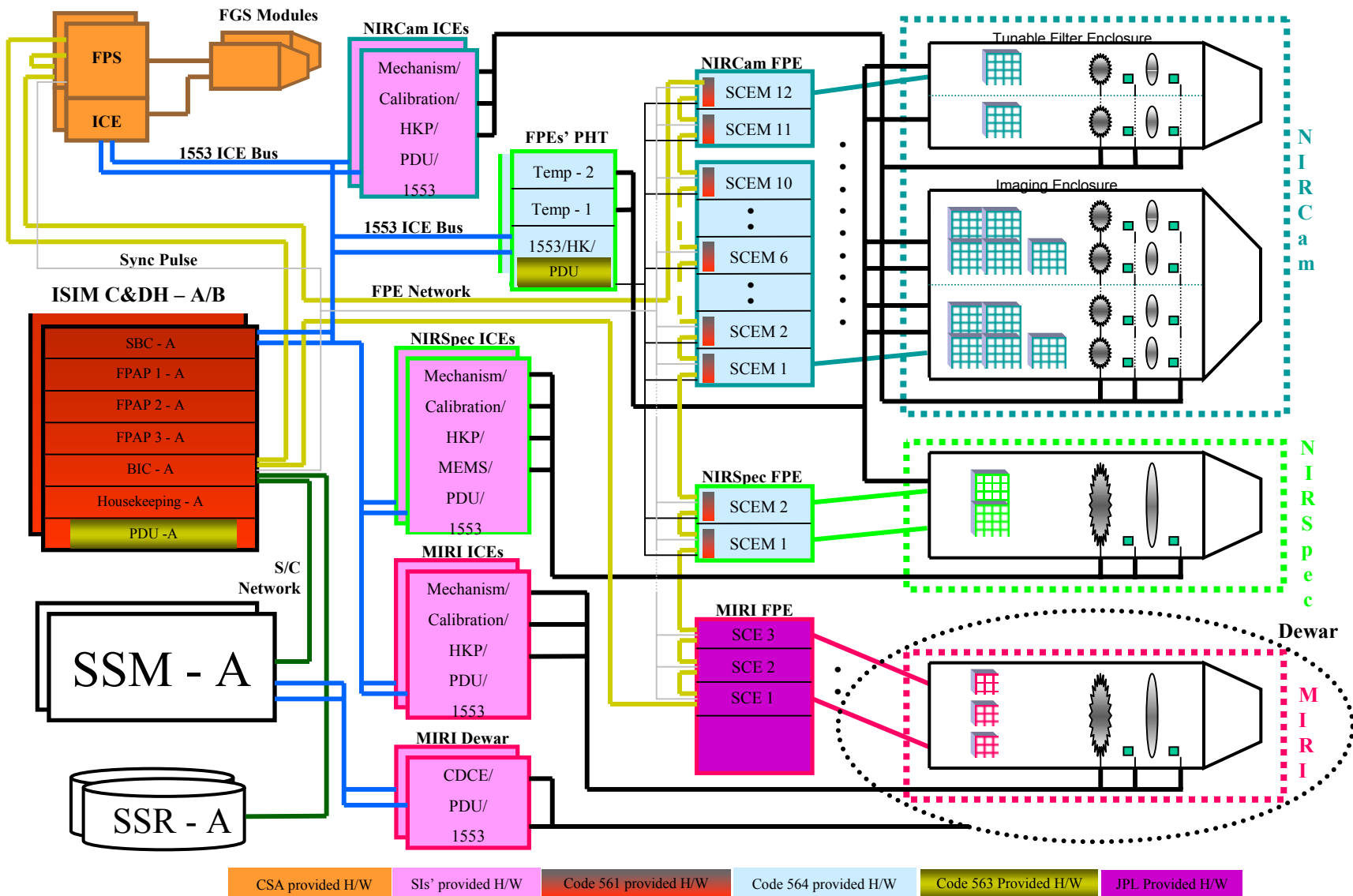


MIRI Requires Active Cooling







Baseline: Warm launch with solid hydrogen cryostat
Optics module ~ 7 K isothermal, 6.9 K detectors

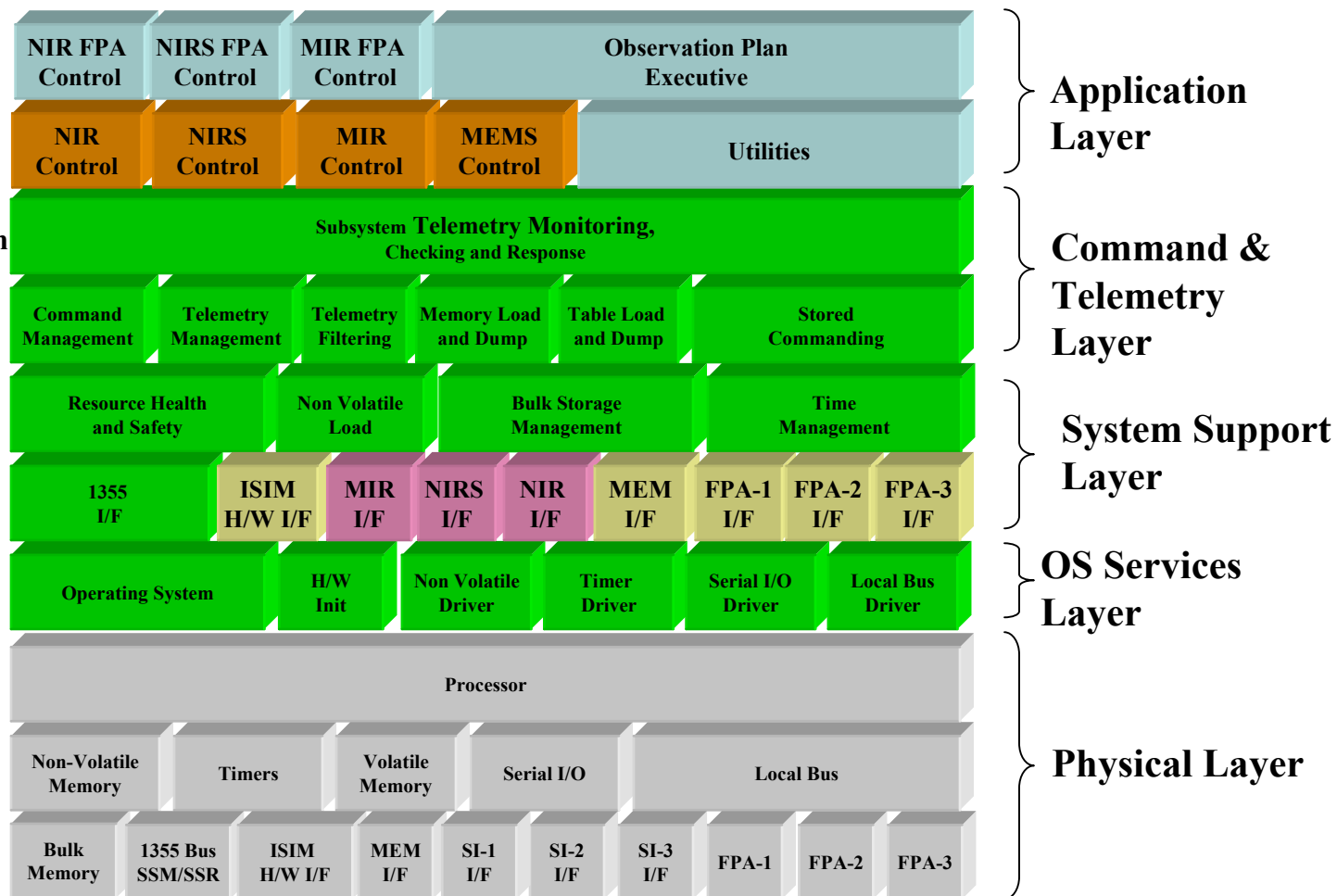


ISIM Electronics Designed to Support Detector Noise Goals, Minimize LCC, and Provide Clean SI Interface



FSW Designed for Low LCC and Clean SI Interface

-  ISIM Application - ISIM
-  ISIM Application – PI Team
-  ISIM C&DH - ISIM
-  Common C&DH
-  ISIM C&DH – PI Team
-  ISIM Hardware



- Common command and telemetry interface to ground
- Simplified I&T
- Reduced NRE cost



ISIM / SI Team Interface



- Close knit teaming relationship between ISIM and instrument PIs is key to success of integrated (shared services) approach
- Science instrument PIs are the customers for ISIM supplied shared services
 - Instrument PIs in design review/approval chain
 - Instrument teams involved in engineering design formulation
 - E.g., detector and C&DH electronics
- Our approach to instrument interface definition involves:
 - Frequent in-depth interaction with SI teams
 - Concurrent engineering when needed
 - Design for ease of I&T
 - Clear science requirements flow-down
 - Science requirements defined/refined by SWG and SI teams



ISIM Technology Development



● Detectors

- Near-Infrared (0.6 - 5 μm)
 - NIRCam, NIRSpec
- Mid-Infrared (5 -28 μm)
 - MIRI

● MEMS Micro-Shutters

- NIRSpec aperture control



Detector Development Program



● Objective:

- Demonstrate large-format, low-noise arrays which satisfy JWST requirements and approach JWST goals
- Establish technologies, designs, and processes so that detector vendors can proceed directly into a flight hardware build phase upon selection

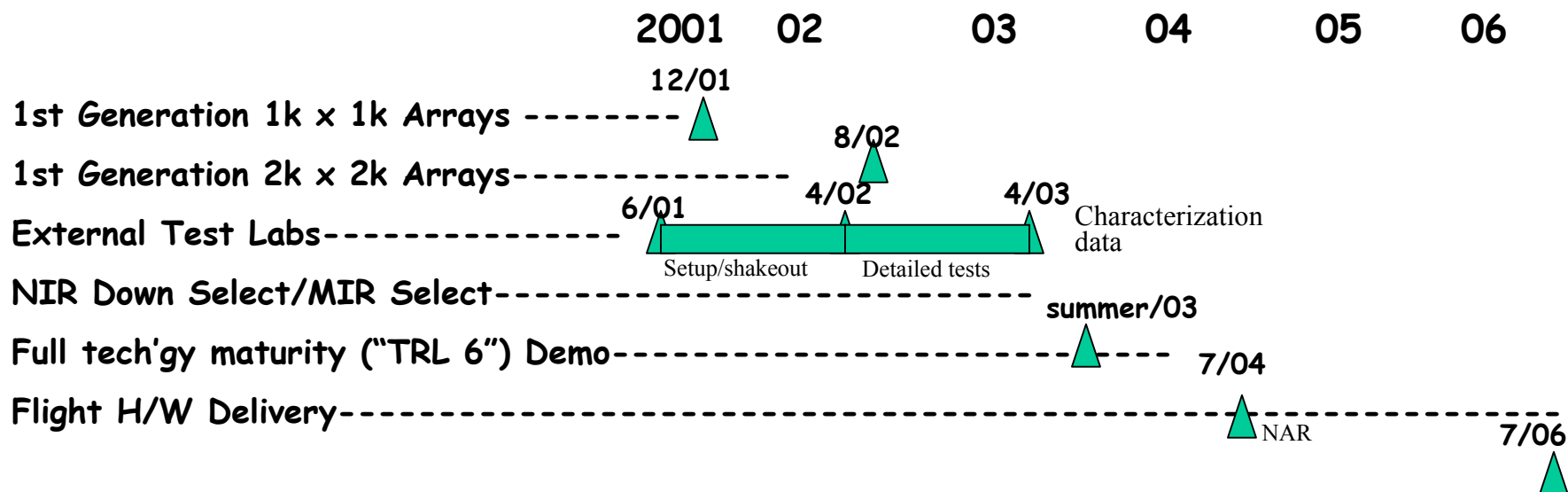
● In place contracts resulting from free and open competitive solicitations:

- Near IR (0.6 - 5 μm): improve sensitivity, optimize manufacturing processes, & develop packaging concepts.
 - Winners: InSb (Raytheon w/ U. Rochester) & HgCdTe (Rockwell w/ U. Hawaii)
- Mid IR (5 - 28 μm): improve sensitivity & cryo readouts
 - Winner: Si:As (Raytheon)
- External labs to fully characterize above technology products
 - Winners: Near-IR: U. Hawaii, U. Rochester, STScI, Mid-IR: ARC

● Flight focal plane vendors: Selection June 03

Development Status & Schedule

- Promising, focused array development progress from qualified competitors (NIR & MIR arrays) '98 - '03. Prototype SCAs and readouts under test. Key NIR focal plane implementation technologies (packaging & manufacturing) also being developed.
- Strong independent test lab network established.
- On track for FY03 down select, FY04 NAR, & eventual flight hardware deliveries.

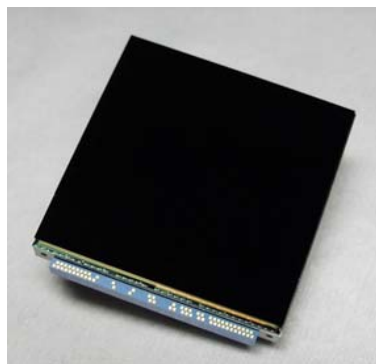


Tech Development Status: HgCdTe

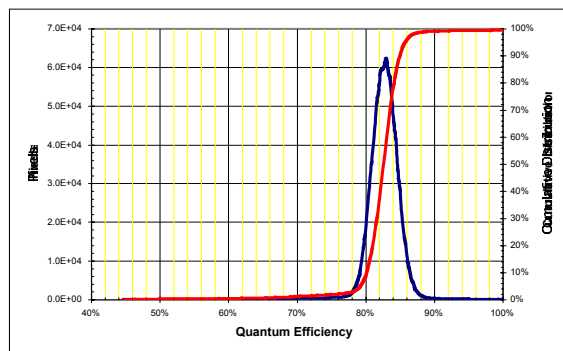
Rockwell Scientific Company (RSC), w/ U. Hawaii (D. Hall)

Hybrids produced and under test at RSC, UH, STScI, & ARC

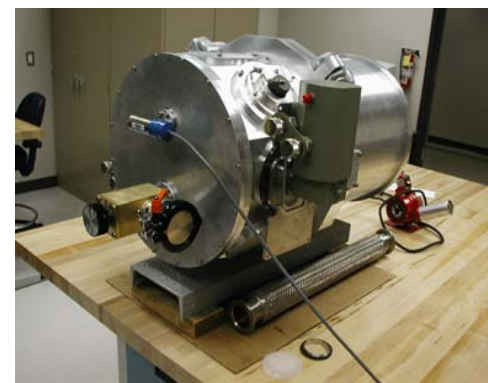
- 1 k x 1 k **HAWAII-1RG** hybrids: 37 K UH data show ~10 e- CDS (Fowler 1) read noise, ~0.005 e-/s dark current, ~80% QE (RSC), with successful removal of CdZnTe substrate (opens visible response). Mux successfully rad-tested.
- 2 k x 2 k **HAWAII-2RG** hybrids: 4 produced to date; UH data forthcoming. Yield of H-2RG readouts was 64% (sci grade). Expect same sensitivity as H-1RG. 1 H-2RG bare mux in test at STScI.
- Pathfinder AR coat successfully applied. Packages for 4 k x 4 k in fab.
- RSC ASIC chip (clock & bias generation adjacent to the focal plane, plus cold 16-bit A/D conversion) in final layout stages. Should have parts in ~6 weeks.



2 k x 2 k SCA



H-1RG QE plot (83% avg at K)



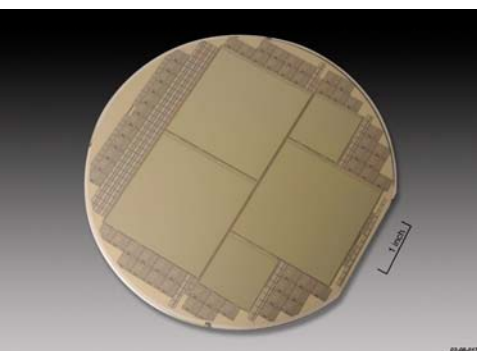
UH ULB Test Chamber

Tech Development Status: InSb

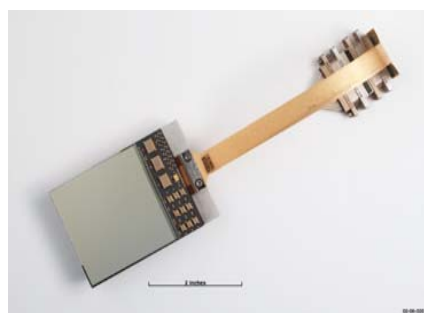
Raytheon IR Operations w/ U. Rochester (Forrest, Pipher)

Hybrids produced & under test at RIO & UR

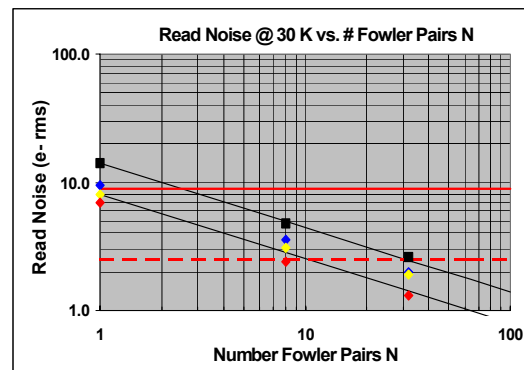
- 1 k x 1 k InSb arrays on **SB-226** & **-291** muxes: 2.4 e- bare mux noise (30 K, Fowler 8); ~6-7 e- for SCA. 0.02 e-/s dark current, ~95% QE, 99.7% operability. Bare muxes & hybrids to be delivered to STScI & ARC soon.
- 2 k x 2 k **SB-290** & **SB-304** muxes fabricated & screened. Design features (incl. ref pixels) verified; yields adequate. UR evaluation to start soon. Expect same sensitivity as for 1 k x 1 k
- Broadband AR coating produced & tested (incl. LN₂ cycling).
- Packages for 4 k x 4 k module: parts fabricated; will be assembled soon.



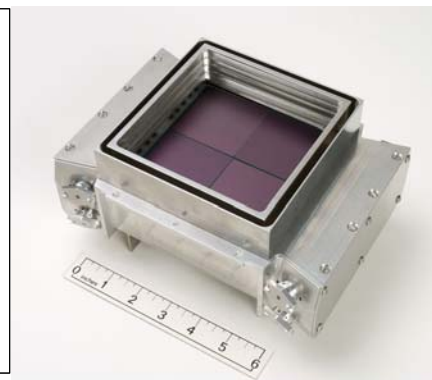
2 k x 2 k & 1 k x 1 k Readouts



2 k x 2 k Module



Bare-mux noise of ~2.4 e- rms, 30 K, Fowler 8 (UR data)

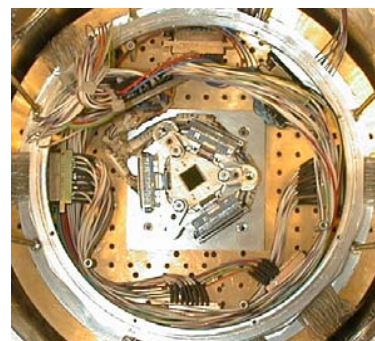


4 k x 4 k Flight-like Package (contains 4 modules)

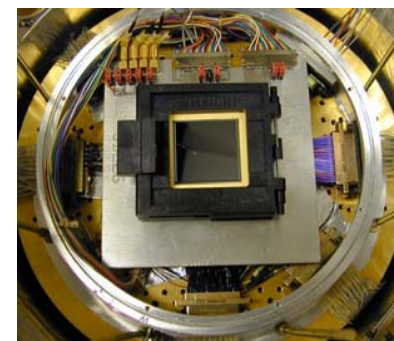
Tech Development Status: Si:As

Raytheon Infrared Operations, contract / tests via ARC

- Full-size MIRI prototype Si:As produced
- Shown to have comparable sensitivity to SIRTf IRAC arrays after 16x scale up. Dark current $\sim 0.02 \text{ e-/s}$ @ 6 K.
- Follow-on development contract, in coordination w/ JPL.



256 x 256 (SIRTf/IRAC)
12/98



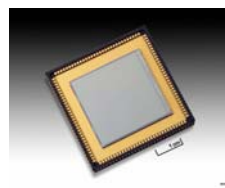
1024 x 1024 (JWST)
3/01

Two full iterations funded; 20 month duration.

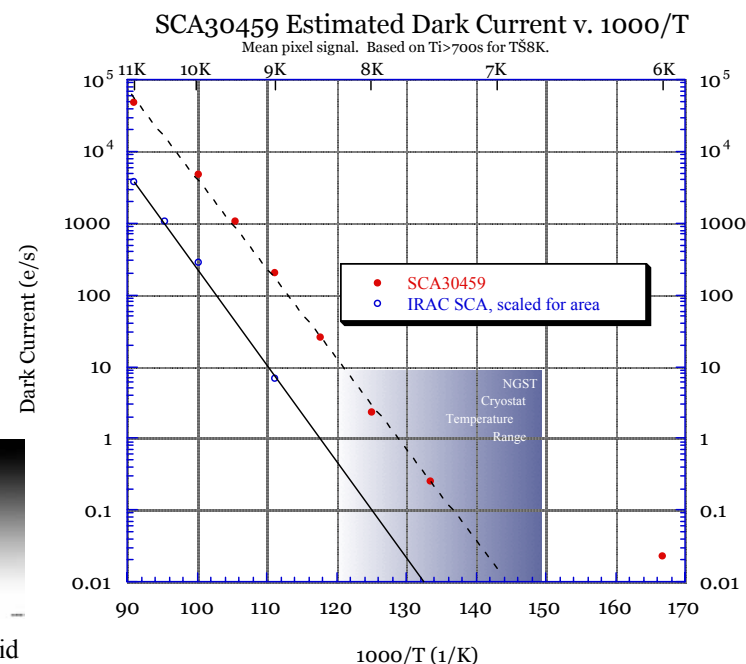
Improved cryo-CMOS readouts (SB-291; ref pixels) in fab (Supertex)

Improved Si:As detectors (enhanced short-wave response) in fab

Lab tests & proton tests upon delivery (3/03)

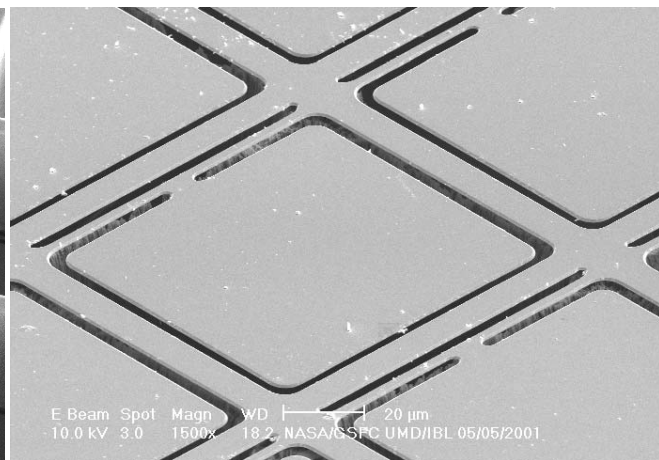
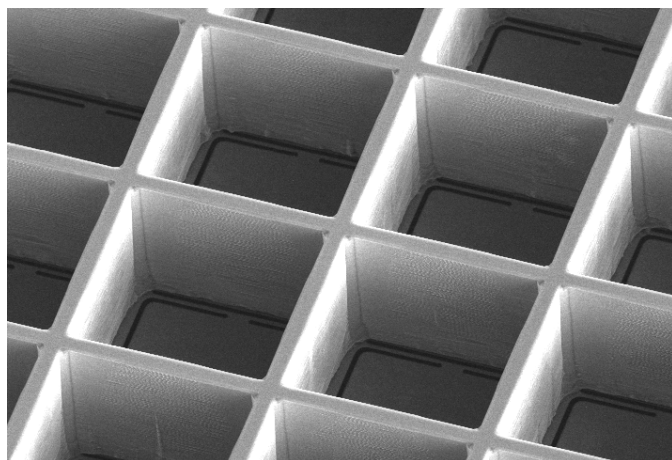


1024 x 1024 hybrid
/ SB-291 mux

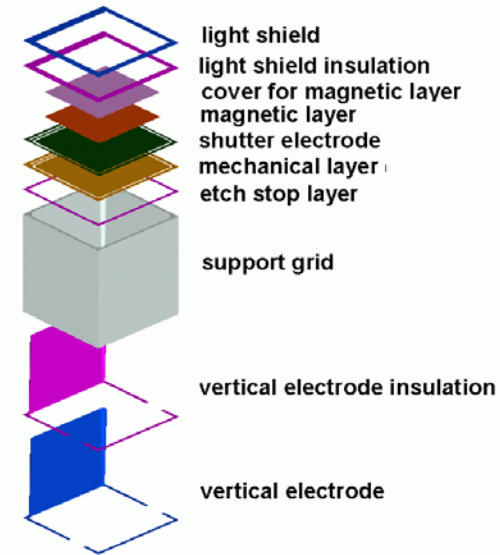
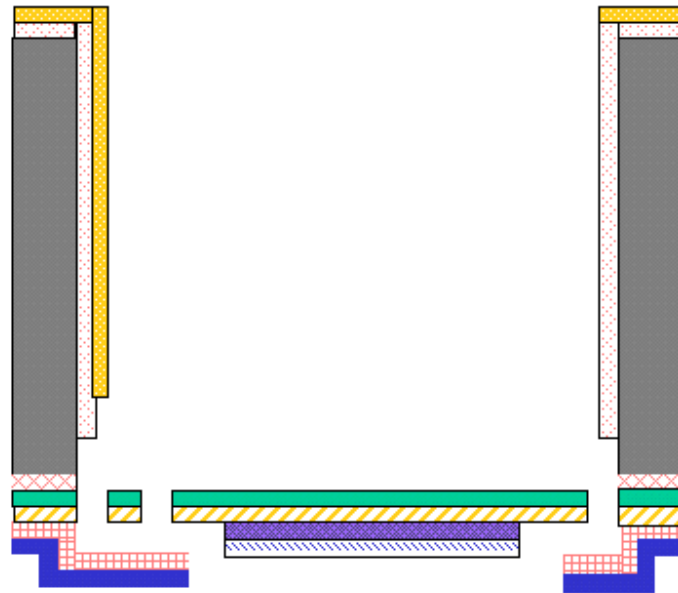


NIRSpec Programmable Aperture Mask









- Format - 1800 x 900 elements, Cell Size - $100\mu\text{m} \times 200\mu\text{m}$
- Operating Temperature - 30 - 35 K
- Efficiency and Blocking
 - > 0.70 when open, < 0.00035 when closed
- Reliability - $\sim 10^6$ cycles
- Power - 35 mW average dissipation



Cross Section of Unit Cell



Exploded View

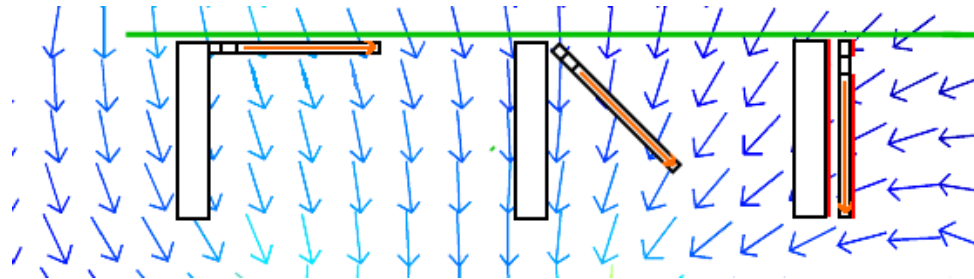
	Light Shield: Aluminum		Magnetic Pad: CoFe
	Support Grid: Silicon		Shutter Mechanical Layer: Silicon Nitride
	Etch Stop: Silicon Dioxide		Vertical Electrode: Gold
	Interconnect/Shutter Electrode: Gold		Vertical Electrode Insulator: Aluminum Oxide
	Light Shield Insulator: Silicon Dioxide		Magnetic Pad Passivation: Aluminum

Micro-shutter Magnetic Actuation



External magnetic field moves shutter open

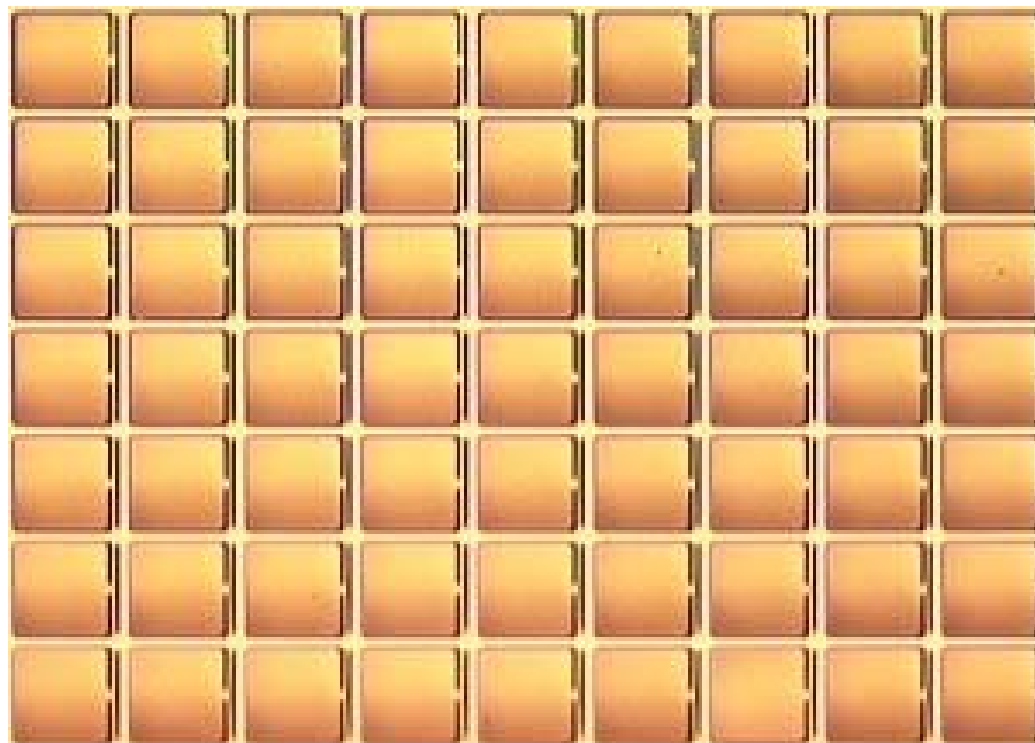
Shutter is moved down
as it is moved through magnetic field



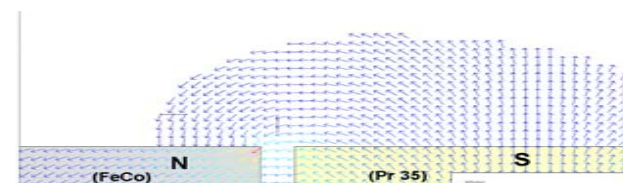
Magnetic metal on shutter
is magnetized

Shutter is electrostatically captured
and held in vertical position

All aspects of magnetic actuation and hold have been demonstrated

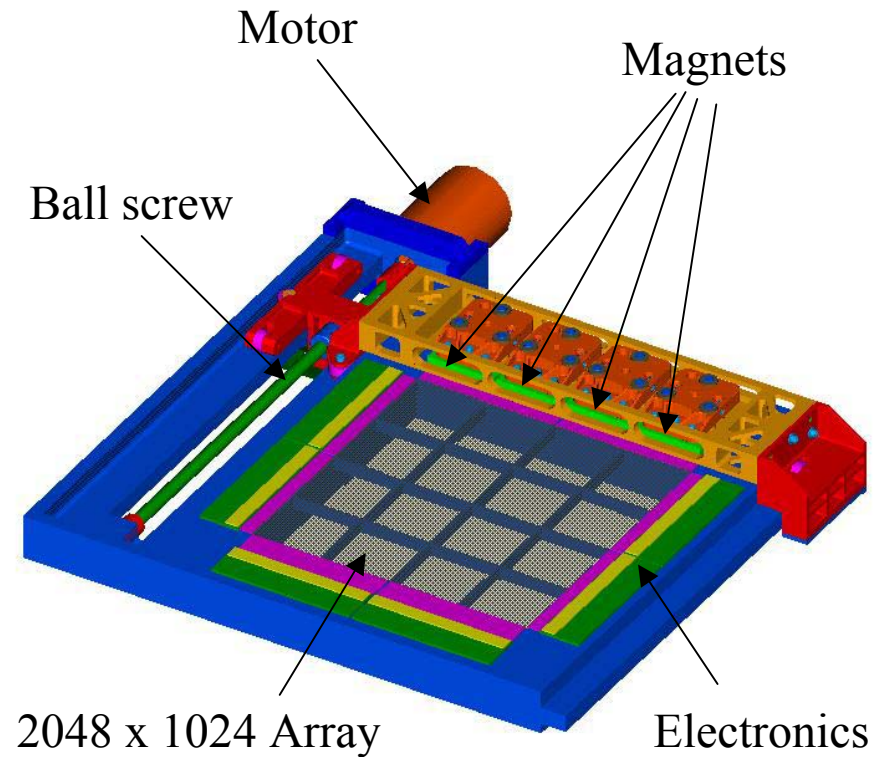
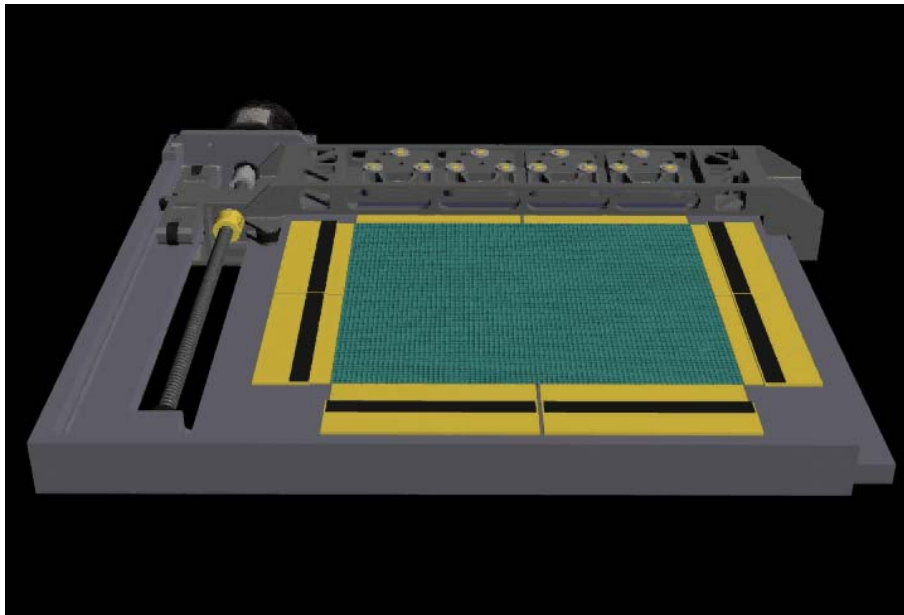


**Microscope images
were made with shutter
edges in focus**



Shutter Mask Assembly Conceptual Design

- Mechanism translates magnet over array
- Four individually aligned permanent magnets provide field
- Drive electronics surround array



The Road Ahead



● Phase B

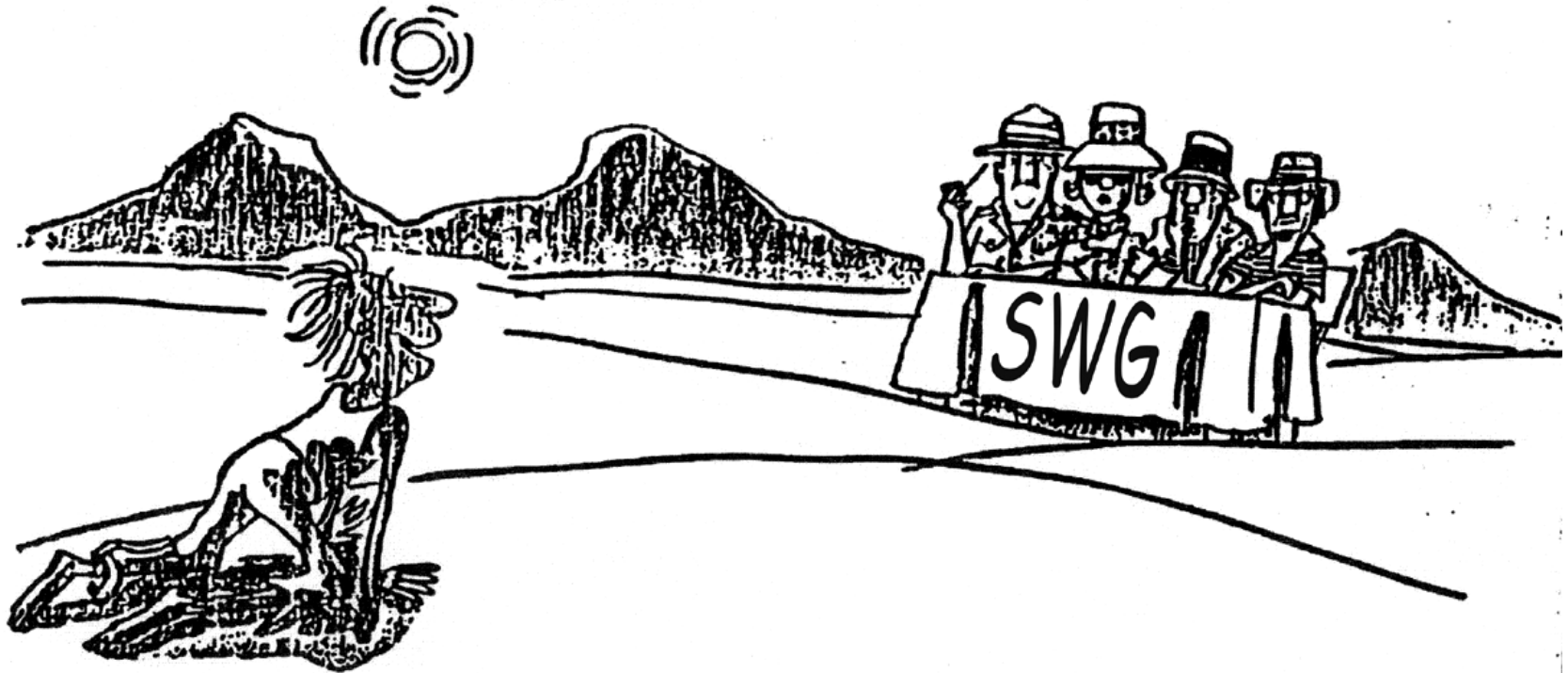
- ✓ Acquire the JWST scientific investigations & select SWG
- Procure science instruments and FGS
 - ✓ NIRCам contract in place
- Procure long lead components
 - flight detectors
 - ✓ NIRSPEC MEMS aperture mask
- Complete requirements and interface definition
- Complete detailed design and make/buy decisions
- Produce bread board and ETU systems



● Phase C/D

- Design, build, integrate, and test flight and GSE systems
- Receive SI's and integrate, test, and qualify the ISIM
- Deliver ISIM to prime contractor and support observatory I&T through launch
- Support on orbit verification

- **Extensive Phase 1 activity leaves the ISIM Project well positioned for the start of Phase 2**
 - Top level science requirements in place (ASWG, ISWG)
 - All instrument teams formed and working (NIRCam, NIRSpec, MIRI, FGS)
 - Implementation team and management organization for in house work in place
 - Project Manager: Bob Smith, Shared Services Manager: Tom Venator
 - Chief Systems Engineer: Matt Jurotich
 - ~ 50 engineers, scientists, and support staff at this point
 - Systems engineering development:
 - Level 2 requirements, instrument IRDs, ISIM/OTE IRD, budget allocations and tracking developed to appropriate level
 - Level 3 requirements development well underway
 - Integrated schedule and PERT network, GSE definition developed to appropriate level
 - Risk management plan under development
- **ISIM technology development program in place, running smoothly, and on track to meet TRL 6 by NAR requirement.**
- **Long lead procurements on track**



Thank god. A panel of experts!